

Overclocking Intel® Core Processors: Taking Overclocking to the Next Level

Dan Ragland – Overclocking Architect, Intel Corp.

Jayashree Bhargava – Application Engineer, Intel Corp.

"HiCookie" – Overclocking Guru, GIGABYTE

RPCS006





WARNING: Altering clock frequency and/or voltage may: (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications. Intel assumes no responsibility that the processor, including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose.

For more information, visit:

http://www.intel.com/consumer/game/gaming-power.htm



Over a Decade of Extreme Edition Innovation!



Our commitment to innovation in overclocking continues!

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Taking Overclocking to the Next Level in 2014 and beyond

- Intel[®] Core[™] i7-4790K Processor: Enhanced for overclocking
- First unlocked Intel[®] Pentium[™] SKU for overclockers
- NEW Intel[®] Core[™] i7 Processor Family on LGA 2011-v3 socket with X99 Chipset
 - First 8-Core overclock-able Intel® processor based desktop
 - First DDR4 based Intel desktop platform









- Overclocking Theory
- High-end Desktop Overclocking Architecture
- Desktop Overclocking Architecture
- Overclocking Ecosystem
- Summary

Agenda

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Defining Overclocking

- What is Overclocking (OC)?
 - The process of increasing clock rates beyond specification
- Why Overclock?
 - Increase performance for compute intensive tasks, e.g., transcode, gaming, rendering
 - Compete, Promote, Socialize
- How is this done?
 - Obtain a motherboard optimized for unlocked Intel® processors
 - Change unlocked ratios or platform clock frequency
 - Increase voltage on relevant interfaces
 - Improve cooling on overclocked/overvoltaged components

Overclocking General Approach

- Apply aggressive cooling to CPU and VRs
- Increase the allowable power and current on the CPU
 - Turbo Power Limits: PL1, PL2
 - IccMax current from the VR
- Select voltages to support frequency on each interface impacted
- Increase frequency
 - Core: Increase your per active core turbo ratios
 - Processor Graphics: Increase your graphics ratios
 - Memory: Increase your memory ratio and associated timings
- Repeat above with different frequency and voltage combinations

Methods differ for each usage scenario

Remember: Maximize frequency, minimize voltage and improve cooling to meet specific stability requirements

What	Why	How
Processor Cores	Rendering, Music, Photo and Video editing, Transcode, Gaming Physics, AI, Compute Intensive	 ✓ Increase power limits and max current ✓ Raise core voltage ✓ Increase active core ratios
Processor Graphics [†]	Gaming frame rates, Media Transcode	 ✓ Increase power limits and max current ✓ Raise processor graphics[†] voltage ✓ Raise processor graphics max ratio
Memory	Processor Graphics performance, Sound engineering, Photo and Video editing	 ✓ Increase memory ratio ✓ Raise memory IO voltage ✓ Change timings ✓ Increase system agent voltage
Platform Base Clock	Affects all of the above	 ✓ Increase all domain voltages ✓ Reduce weakest domain frequency via ratios



Overclocking Theory: VR Airflow provides > power out put





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Intel[®] Core[™] i7-5960X Processor Extreme Edition Overclocking Intel's First 8-Core Desktop Processor



- New! 8 Cores, 16 Threads
- New! 4 channel DDR4-2133 memory support
- 3.0 GHz base frequency
- Up to 3.5 GHz Turbo frequency
- Fully unlocked for performance tuning
- 20 MB Intel[®] Smart Cache
- Intel[®] Turbo Boost Technology 2.0
- Intel[®] Hyper-Threading Technology
- Supports LGA 2011-v3 socket
- 40 PCI Express* 3.0 lanes



....highest desktop core count and it overclocks amazingly well !!!

Intel[®] Core[™] i7 Processors for high-end desktop: Based on Socket LGA 2011-3 with Intel[®] X99 Express Chipset



🚾 Core Frequency

- Unlocked Intel[®] Turbo Boost Technology Limits
- Unlocked core ratios up to 80 in 100MHz increments
- Programmable voltage offset and override voltage via iVR

🚳 Memory Ratio

- Unlocked memory controller Unlocked memory controller voltage levels
- Granularity options for 200 and 266MHz
- DMICLK (aka BCLK)
 - Unlocked PCH clock controller (<1MHz increments upwards of 200MHz)

🔊 💿 PEG and DMI Ratios

- Variable BCKL: PEG/DMI ratios 5:5, 4:5, 3:5, for BCKL@ 100, 125, and 167 MHz

Voltage Planes



- V_{CCIN}: SVID 1.8V Nom up to 2.3V+, static V up to 3.0V
- V_{CORE}: dynamic additional V, static V up to 2.0 V
- V_{RING}: dynamic additional V, static V up to 2.0 V

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• V_{DDQ} : 1.2V Nom for DDR4

Processor Core Voltage Control Modes

 Default Voltage/Freq curve

 Offset (+/-) is applied to the entire curve and can be combined with Override or Interpolation



- Interpolation (adaptive) in the overclocking region: Target Based
- Override applied to the entire curve. Used for extreme OC Tradeoff: higher power and lower reliability.

Clock Tree: BCLK Tuning



- Single BCLK input comes from PCH in <1MHz steps
- Acceptable input to CPU limited by PCI Express* (PCIe*) and DMI PLL interface:

100MHz x ±5-7% PEG/DMI @ 5:5 125MHz x ±5-7% PEG/DMI @ 5:4 167MHz x ±5-7% PEG/DMI @ 5:3

 Frequency Relationships f(Core) = BCLK*Core Ratio F(Ring) = BCLK*Ring Ratio f(DDR) = BCLK*1.33*DDR Ratio -or-

f(DDR) = BCLK*1.00*DDR Ratio

Intel[®] Core[™] i7 Processors for Desktop Based on Socket LGA2011 with Intel[®] X99 Express Chipset

	inside CORE 17	inside CORE ⁻ i7	inside CORE 17
SKU	i7-5960X	i7-5930K	i7-5820K
Cores	8	6	6
Clock Speed / Max Turbo Frequency	3.0 GHz / 3.5 GHz	3.5 GHz / 3.7 GHz	3.3 GHz / 3.6 GHz
Cache / PCI Express [*] Lanes	20 MB / 40 lanes	15 MB / 40 lanes	15 MB / 28 lanes
Turbo Ratio Overrides	Up to 80	Up to 80	Up to 80
PL1, PL2, Tau, ICCMax Overrides	√	√	\checkmark
Real-time Core Overclocking (in OS)	Yes	Yes	Yes
DDR Frequency Ratio Overrides [†]	Up to 2667	Up to 2667	Up to 2667
DDR Timing Overrides	√	√	√
Coarse BCLK Ratios	1.0, 1.25, 1.67	1.0, 1.25, 1.67	1.0, 1.25, 1.67

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¹⁷ [†]Memory ratio capabilities above 2667 via ratio not tested; use BCLK for highest frequencies.

Live Demonstration¹: Overclocking the Intel® Core™ i7-5960X Extreme Edition Processor

18





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4th Generation Intel[®] Core[™] Processors



PCIe = PCI Express*





Core Frequency

- Unlocked Intel® Turbo Boost Technology limits†
- Unlocked core ratios up to 80 in 100MHz increments[†]
- Programmable voltage via iVR
- Processor Graphics Frequency (pGfx)
- Unlocked Intel[®] HD Graphics limits†
- Unlocked graphics ratios up to 60 in 50MHz increments
- Programmable voltage via iVR
- Memory Ratio
 - Unlocked memory controller
 - Options for 200 and 266MHz steps†
 - Logical ratios up to 2933MHz†
- DMICLK (aka BCLK)
 - Unlocked PCH clock controller (1MHz increments upwards of 200MHz)†

PEG and DMI Ratios

 Variable ratios 5:5, 4:5, 3:5 (for BCKL @ 100, 125, and 167 MHz)†



Voltage Planes



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21

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Clock Tree



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100MHz x ±5-7% PEG/DMI @ 5:5 125MHz x ±5-7% PEG/DMI @ 5:4 167MHz x ±5-7% PEG/DMI @ 5:3

Frequency Relationships

 f(GT) = BCLK/2*GT Ratio
 f(Core) = BCLK*Core Ratio
 f(Ring) = BCLK*Ring Ratio
 f(DDR) = BCLK*1.33*DDR Ratio
 -Or

f(DDR) = BCLK*1.00*DDR Ratio

Ratio Tuning Capability Summary



Desktop: 4th Generation Intel[®] Core[™] Processors

Intel® Z97 Express Chipset Intel H97 Express Chipset	inside CORE i7	[‡] Others	
Turbo Ratio Overrides	Unlocked Processors [™] √	No	†Unlocked Processors:
DDR Frequency Overrides	√ (√	<u>Intel® Core™</u> • i7-4790K, i7-4770K
Fine BCLK Overrides	√ 1	√ ¹	 i5-4690K, i5-4670K <u>Intel[®] Pentium[™]</u> G3258
Coarse BCLK Ratios	√ ²	No	[‡] This includes all other overclocking locked
iVR Overvoltage	√	√	Intel® Core™ i3, Intel® Pentium™, and Intel® Celeron™
PL1, PL2, Tau, ICCMax Overrides	√	√	¹ Actual Fine BCLK frequency adjustments will be limited. ~5%
DDR Timing Overrides	✓	√	² Coarse BCLK Ratios (1.0, 1.25, 1.67) are unlocked with K SKU processors only
pGfx Ratio Overrides	√	√	capabilities are subject to change.

Mobile: 4th Generation Intel[®] Core[™] Processor Overclocking[†]

Summary:

- Core overclocking on select Intel[®] Core[™] i7 SKUs
- Graphics and memory overclocking on all Intel Core i7 and Core i5 based -H, -M, and -U series processors

	Intel Core processor	Turbo Ratio Overrides	Processor Graphics Ratio Overrides	iVR Over- voltage	BCLK Coarse ⁽¹⁾	BCLK Fine ⁽¹⁾
	i7-4930MX	Unlimited	\checkmark	\checkmark	\checkmark	\checkmark
-H and	i7-4900MQ	6 bins	\checkmark	\checkmark	\checkmark	\checkmark
-M Series	i7-4950HQ	6 bins	\checkmark	\checkmark		\checkmark
	i7-4800MQ	4 bins	\checkmark	\checkmark	\checkmark	\checkmark
(intel)	i7-4850HQ	4 bins	\checkmark	\checkmark		\checkmark
inside" CORE 'i7	i7-4702MQ	2 bins	\checkmark	\checkmark	\checkmark	\checkmark
	i7-4700MQ	2 bins	\checkmark	\checkmark	\checkmark	\checkmark
(intel)	i7-4750HQ	2 bins	\checkmark	\checkmark		\checkmark
inside" CORE"i5	i5	none	\checkmark			\checkmark
	i3	none				
-U Series	i7-4600U	4 bins	\checkmark	\checkmark		
	i7-4650U	4 bins	\checkmark	\checkmark		
	i7-4558U	4 bins	\checkmark	\checkmark		
	i5	none	\checkmark			
	i3	none				
-Y Series	All	none				

¹Requires Intel[®] HM87 or QM87 chipsets and results will vary. [†]Actual overclocking results will vary and capabilities are subject to change.

Live Demo: Intel® Pentium™ G3258 Overclocking with Intel® Extreme Tuning Utility



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Intel[®] Extreme Memory Profile for DDR4 Intel[®] Core[™] i7 Processor Family for LGA 2011-v3



Quad Channel DDR4 Memory Kits

- Performance-oriented expansion of standard DDR4 memory specification
- Memory DIMM kits certified for four channel mode, ensuring optimal performance
- Designed for ultimate flexibility with predefined and certified memory optimizations
- Intel "Supports" Identifier badge on memory packaging for easy identification in retail

Partial list of Intel[®] Extreme Memory Profile (Intel[®] XMP) certified memory vendors. Consult motherboard manufacturers and memory vendors for Intel XMP support details.

Get ready for DDR4 Overclocking!

- First desktop DDR4 platform launched Aug 29th, 2014
 - 2,133 MT/s is the supported frequency
- Amazing overclocking results[†] on day-1
 - Ratio based OC up to 2667 MT/s; much higher with BCKL OC'ing
 - Up to 2,800 MT/s without voltage increase (1.2v)
 - Modules at 3,200 MT/s and beyond available today!!!
- Look for DDR4 Intel[®] XMP 2.0 certified modules



³⁰ Intel[®] Extreme Memory Profile (Intel[®] XMP)









- New Intel [®] XMP 2.0 spec released for DDR4
- Enables speeds, latencies above JEDEC specification.
 - Easy, robust, overclocking solution designed to take advantage of the unlocked capability of Intel[®] Core[™] Processors
 - Predefined and tested profiles can be selected in BIOS
- Intel XMP compliant DIMMs available
 - Intel XMP Ready: Module has been programmed with an uncertified profile GOOD
 - Intel XMP Certified: Module has passed supplier test and submission process for specific CPU and motherboard BEST
 - Adata, Corsair^{*}, G.Skill^{*}, Kingston^{*}, Patriot^{*}, Crucial^{*} and others

Certifications posted at:

http://www.intel.com/consumer/game/extreme-memory.htm

lemory Slot Select	tion —			
Slot #1 👻	DDR4			
Module Size	8192 1	IBytes	Correction	
Max Bandwidth	DDR4-2133	(1066 MHz)	Registered	
Manufacturer	Crucial Te	chnology	Buffered	
Part Number	CD1G641	6Z80AD2J	SPD Ext.	XMP 2.0
Serial Number	AA01	AA018FFE		
Fimings Table	JEDEC #9	JEDEC #10	XMP-2400	XMP-2400
Frequency	1066 MHz	1066 MHz	1200 MHz	1200 MHz
CAS# Latency	18.0	20.0	16.0	16.0
RAS# to CAS#	15	15	16	15
RAS# Precharge	15	15	16	15
tRAS	36	36	40	39
tRC	50	50	55	55
Command Rate				
Voltage	1.20 V	1.20 V	1.200 V	1.200 V

System boots with highest supported JEDEC defined parameters by default



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CPU Caches Mainboard Memory SPD Graphics About								
- Memory Slot Selection								
Slot #1 🔹	DDR4	DDR4						
Module Size	4096 N	IBytes	Correction					
Max Bandwidth	DDR4-2133	(1066 MHz)	Registered					
Manufacturer	Cor	sair	Buffered					
Part Number	CMK16GX4M	4A2800C16	SPD Ext.	XMP 2.0				
Serial Number Week/Year								
Timings Table								
F	JEDEC #/	JEDEC #0	AMP-2000	AMP-2990				
Frequency	1066 MHZ	1066 MHZ	1400 MHz	1499 MHZ				
CAS# Latency	15.0	16.0	16.0	16.0				
RAS# to CAS#	15	15	18	18				
RAS# Precharge	15	15	18	18				
tRAS	36	36	36	39				
tRC	50	50	54	70				
Command Rate								
Voltage	1.20 V	1.20 V	1.200 V	1.350 V				

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Certifications posted at:

http://www.intel.com/consumer/game/extreme-memory.htm

CPU-Z								
Memory Slot Selection								
Slot #5 DDR4								
Module Size	4096 N	1Bytes	Correction					
Max Bandwidth	DDR4-2133	(1066 MHz)	Registered					
Manufacturer	G.S	Skill	Buffered					
Part Number	F4-3333C	16-4GRK	SPD Ext.	XMP 2.0				
Serial Number Week/Year								
Timings Table								
Frequency	1066 MHz	1066 MHz	1666 MHz	47483648 M				
CAS# Latency	18.0	19.0	16.0	147483648.				
RAS# to CAS#	15	15	16	0				
RAS# Precharge	15	15	16	0				
tRAS	35	35	36	0				
tRC	50	50	52	0				
Command Rate								
Voltage	1.20 V	1.20 V	1.350 V	0.000 ∨				
CPU-Z Ver. 1.70.1.x64 Tools 🔻 Validate OK								

System boots with highest supported JEDEC defined parameters by default



Live Demo: DDR4 Overclocking on Intel® Core™ i7-5960X Processor



Intel[®] Extreme Tuning Utility (Intel[®] XTU)

Simple-to-use
 Windows^{*} application

- Exposes processor & PCH knobs for performance tuning by user
- Real-time adjustment of key settings without rebooting¹
- Version 5.1 now available for download from Intel or other motherboard suppliers[†]

Intel® Extreme Tun	ing Utility		des des productions des la construcción de la const				Mor	nitoring 😢 Help
stem Information	Processor				^ î	Processor	Default	
inual Tuning	Reference Clock ③	100.0 MHz	Max Non Turbo Boost	Ratio 🛈	31 x	Reference Clock	100.0 MHz	100.0 MHz
All Controls						Max Non Turbo Boost Ratio Max Non-Turbo Boost CPU Sp	31 x 3.100 GHz	31 x 3.100 GHz
rocessor •	Enhanced Intel® SpeedStep Technology @ C		Intel® Turbo Boost Tec	hnology © ©		Max Turbo Boost CPU Speed	3.800 GHz	3.800 GHz
iemory	Disable Enable	46 000 4	Disable	thable	112,000 A	Enhanced Intel® SpeedStep T	Enable	Enable
oitages	Processor Graphics Current Limit @ 0	46.000 A	Core Current Limit		112.000 A	Intel® Turbo Boost Technology	Enable	Enable
ohics Tuning	Additional Turba Malkana 🖉 🗇	0.00000	Deserves Complian Dat	- 1	12.0.1	2 Active Cores	36 x 37 x	38 x 37 x
ss Tests	Additional Turbo Voltage 000	0.00000 mv	Processor Graphics Rat		15.0 X	3 Active Cores	36 x	36 x
iles	Additional Deserves Complian Vallage	0 00000	Turke Reast Short Daw	or May Enable . (D		4 Active Cores Core Current Limit	36 x 112.000 A	112.000 A
	Additional Processor Graphics Voltage	0.00000 mv	Turbo Boost Short Pow			Additional Turbo Voltage	0.00000 mV	0.00000 mV
			Disable	Enable		Processor Graphics Ratio Limit	13.0 ×	13.0 x
	Turbo Boost Short Power Max (1)	69 W	Turbo Boost Power Ma	× 🛈	55 W	Additional Processor Graphics	0.00000 mV	0.00000 mV
	-					Turbo Boost Short Power Max	68 W	69 W
	Overclocking Enable 00		Turbo Boost Power Tim	e Windc 28.0000	0000 Seconds	Turbo Boost Power Max Overclocking Enable	55 W Disable	55 W Disable
	Disable Enable					Turbo Boost Power Time Wind	28.00000000	S-28.00000000 S
	Multipliers					Memory		
	1 Active Core		1 38 v I			Memory Multiplier	10 x 1222 MH-	10.00 x
			37			tCL	9	9
			5/ x			tRCD +RP	9	9
	3 Active Cores	© ¢	36 x			tRAS	24	24
	4 Active Cores	<u>ن</u> و	36 x			tRRD tW/R	4	4
						tRTP	5	5
						tWTR tRFC	5 74	5 74
							20	20
	Memory				^			1. C D El-
	Intel® Extreme Memory Profile				- IL			Save to Profile
PU Core Temperature								
				100 %	1343 MB	89 °C		
0 %						Graphics Frequency		
ocessor Frequency				0%	3.59 GHz	350 MHz		
9 GHz					IACore TDP	CPU Fan Speed		
W Total TDP				4	53 W	2857 RPM		
				Memory Frequency	Graphics TDP			
	88		1 Minute –	1333 MHz	0 W			

http://www.intel.com/go/xtu

† Motherboard BIOS must be configured correctly to work with XTU. Contact your motherboard supplier for more information. 1 Available select 3rd and 4th Generation Intel[®] Core[™] Processor SKUs.



Intel® Extreme Tuning Utility and HWBot.org*



Combined Features

- Upload/Download overclocking settings reliably
- Export/Import Intel XTU overclocking settings
- Compare benchmark scores and configurations with others
- Link other benchmark scores to Intel XTU profiles
- Compete with others for higher scores
- Integrated with existing social networks: Facebook* and Twitter*





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Summary

- Innovation in overclocking continues a decade long focus
- Intel[®] Core[™] i7 Processors with the Intel[®] X99 Express Chipset allow increasing Core, DDR, and BCLK frequencies on processors with the highest core count and memory capacity
- 4th Generation Intel[®] Core[™] processors build upon existing overclocking capabilities and new SKUs offer greater OC performance and price points
- We will continue to introduce exciting new overclocking features as demonstrated today!
- Reminder: Intel has not tested, and does not warranty, the operation of the processor beyond its specifications



39

Next Steps

- For designers: full overclocking documentation is available to you under NDA; you will find all details on all these tuning knobs
 - Contact your Intel field rep. for details
- For system OEMs: we encourage you to utilize overclocking while making informed decisions about risks and rewards
 - Use the lowest voltage at the lowest temperature to minimize risk
- For end users: check-out the products and tools shown today
 - Our latest 8-Core desktop processors
 - DDR4 Overclocking
 - Intel [®] Extreme Tuning Utility

Additional Sources of Information

- A PDF of this presentation is available is available from our Technical Session Catalog: www.intel.com/idfsessionsSF. This URL is also printed on the top of Session Agenda Pages in the Pocket Guide.
- Demos at IDF:
 - Overclocking demos of Intel processors and DDR4 memory
- Intel Resources:
 - intel.com/gaming
 - intel.com/go/xtu
 - intel.com/content/www/us/en/gaming/extreme-memory-profile-xmp.html
- Overclocking forums¹:
 - hwbot.org
 - xtremesystems.org

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- Processor Numbering Notice: Intel processor numbers are not a measure of performance. Processor numbers differentiate features
 within each processor family, not across different processor families: Go to: <u>Learn About Intel® Processor Numbers</u>
- Iris[™] Graphics: Iris[™] graphics is available on select systems. Consult your system manufacturer.
- Overclocked Memory: Warning: Altering PC memory frequency and/or voltage may (i) reduce system stability and use life of the system, memory and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel assumes no responsibility that the memory, included if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. Check with memory manufacturer for warranty and additional details.
- Overspeed Protection Removed: Warning: Altering clock frequency and/or voltage may (i) reduce system stability and useful life of
 the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance;
 (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the
 operation of the processor beyond its specifications.
- Intel[®] Turbo Boost Technology requires a system with Intel Turbo Boost Technology. Intel Turbo Boost Technology and Intel Turbo Boost Technology 2.0 are only available on select Intel[®] processors. Consult your PC manufacturer. Performance varies depending on hardware, software, and system configuration. For more information, visit http://www.intel.com/go/turbo.

Risk Factors

The above statements and any others in this document that refer to plans and expectations for the second guarter, the year and the future are forwardlooking statements that involve a number of risks and uncertainties. Words such as "anticipates," "expects," "intends," "plans," "believes," "seeks," "estimates," "may," "will," "should" and their variations identify forward-looking statements. Statements that refer to or are based on projections, uncertain events or assumptions also identify forward-looking statements. Many factors could affect Intel's actual results, and variances from Intel's current expectations regarding such factors could cause actual results to differ materially from those expressed in these forward-looking statements. Intel presently considers the following to be important factors that could cause actual results to differ materially from the company's expectations. Demand for Intel's products is highly variable and, in recent years, Intel has experienced declining orders in the traditional PC market segment. Demand could be different from Intel's expectations due to factors including changes in business and economic conditions; consumer confidence or income levels; customer acceptance of Intel's and competitors' products; competitive and pricing pressures, including actions taken by competitors; supply constraints and other disruptions affecting customers; changes in customer order patterns including order cancellations; and changes in the level of inventory at customers. Intel operates in highly competitive industries and its operations have high costs that are either fixed or difficult to reduce in the short term. Intel's gross margin percentage could vary significantly from expectations based on capacity utilization; variations in inventory valuation, including variations related to the timing of qualifying products for sale; changes in revenue levels; segment product mix; the timing and execution of the manufacturing ramp and associated costs; excess or obsolete inventory; changes in unit costs; defects or disruptions in the supply of materials or resources; and product manufacturing quality/yields. Variations in gross margin may also be caused by the timing of Intel product introductions and related expenses, including marketing expenses, and Intel's ability to respond quickly to technological developments and to introduce new products or incorporate new features into existing products, which may result in restructuring and asset impairment charges. Intel's results could be affected by adverse economic, social, political and physical/infrastructure conditions in countries where Intel, its customers or its suppliers operate, including military conflict and other security risks, natural disasters, infrastructure disruptions, health concerns and fluctuations in currency exchange rates. Intel's results could be affected by the timing of closing of acquisitions, divestitures and other significant transactions. Intel's results could be affected by adverse effects associated with product defects and errata (deviations from published specifications), and by litigation or regulatory matters involving intellectual property, stockholder, consumer, antitrust, disclosure and other issues, such as the litigation and regulatory matters described in Intel's SEC filings. An unfavorable ruling could include monetary damages or an injunction prohibiting Intel from manufacturing or selling one or more products, precluding particular business practices, impacting Intel's ability to design its products, or requiring other remedies such as compulsory licensing of intellectual property. A detailed discussion of these and other factors that could affect Intel's results is included in Intel's SEC filings, including the company's most recent reports on Form 10-Q, Form 10-K and earnings release.

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